Welcome to O-leading

O-Leading strives to be your one stop solution partner in EMS supply chain, including PCB design , PCB fabrication and PCB assembly (PCBA). We provide some of the most advanced PCB technology, including HDI PCBs, multilayer PCBs, Rigid-Flexible PCBs. We can support from quick turn prototype to medium & mass Production.

In general, our global customers are very impressed with our services:rapid response, competitive price and quality commitment.Providing more valuable technical service and overall solution is the way O-leading forward.

Looking to the future, O-leading will concentrate on the innovation and development of electronics manufacturing technology as always, and make persistent efforts on PCB & PCBA one-stop service to provide first-class services and create more value for our customers.

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service – S/S in 24hrs , 4-8layers in 48-96 working hrs production time. HDI PCB manufacturer china

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

Product Description

PCB P/N	Black solder mask pcb with half plated hole		
Layer Count	4L		
Material	FR-4 TG170		
Board thk	1.6mm		
copper thk	1/1/1/1oz		
Smallest hole size	0.3MM		
No. of holes (pcs)	98		
line w/s	5/5mil		
Impedance control. Y / N (Tol %)	N		
Surface Finishing	ENIG Au:0.05-0.10UM		
Solder Mask Silkscreen	Black / White		
Single board size	Dim X (mm):21;Dim Y (mm):12		
Panelisation	Dim X (mm):90;Dim Y (mm):68;No Of UPS:16		
Special:peelable mask	N		
Routing/Punching	CNC		

•

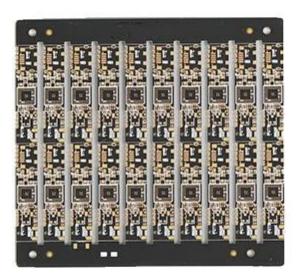












www.o-leading.com

High quality pcb manufacturer

•

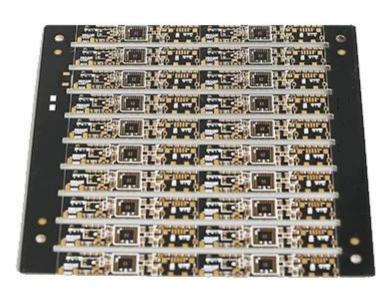












www.o-leading.com

• Printed Circuit Board PCB Manufacturing Company

Our Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT













Certifications





Test Report

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313,FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG,

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ Date of Sample Received: 22 Mar 2019

22 Mar 2019 - 30 Mar 2019 Testing Period :

Test Requested : Selected test(s) as requested by client. Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion :

Based on the performed tests on submitted sample(s), the results of Lead. Mercury, Cadmium, Hexavalient chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/85/EU.

Signed for and on behalf of SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch





Test Report No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

 Specimen No.
 SGS Sample ID
 Description

 SN1
 SZX19-005304.001
 Green*PCB**

(1) 1 mg/kg = 1 ppm = 0.0001% (2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL) (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-DES, UV-Vis and GC-MS.

001 ND 8 Limit 100 Test Item(s) Cadmium (Cd) Lead (Pb) mg/kg 1,000 1,000 1,000 mg/kg mg/kg mg/kg Mercury (Hg) Hexavalent Chromium (Cr(VI)) mg/kg mg/kg mg/kg mg/kg Sum of PBBs 1.000 Dibromobiphenyl Tribromobiphenyl Tetrabromobiphenyl Pentabromobiphenyl Hexabromobiphenyl mg/kg mg/kg mg/kg mg/kg mg/kg mg/kg Heptabromobiphenyl Octabromobiphenyl Nonabromobiphenyl Decabromobiphenyl mg/kg Sum of PBDEs Monobromodiphenyl ether Dibromodiphenyl ether 1,000 mg/kg mg/kg mg/kg Tribromodiphenyl ether Tetrabromodiphenyl ether Pentabromodiphenyl ether



n/Terms-and-Conditions aspx and here specified the conference of t

Max

Max

UL Product iQ™



ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

Cond Width

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F TAI SANG BANK BLDG 130-132 DES VOEUS ROAD CENTRAL, HONG KONG

		Min	Cond	SS/	Area	Solo	der	Oper		Meets	c
	Min	Edge	Thk	DS/	Diam	Lim	its	Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	c	sec	c	Class	DSR	1
Multilayer (m	Multilayer (mass laminate) printed wiring boards.										
O-LEADING- 401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	3	50
O-LEADING- 407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer pri	Multilayer printed wiring boards.										
O-LEADING- 408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer p	rinted wiring b	oards.	Page 1						3 77	Pov	
O-LEADING- 002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING- 003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	A	-
O-LEADING- 033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING- 205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING- 206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING- D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING- S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING- S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	НВ	A	*
O-LEADING- S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

 $[\]mbox{\ensuremath{\star}}$ - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

并不是所有出现在本数据库中的公司名称和产品都满足了UL 跟踪检验服务的要求。只有带有 UL 标志的产品,才应该被视为经过UL认证,并满足UL 跟踪检验服务的要求。注意查看产品上的标志。

UL 允许在线认证目录中所含材料的复制遵循以下条件: 1.指南信息、装配、构造、设计、系统和/或认证(文件)必须在不篡攻任何数据(或图纸)的情况下完整且无误导性地呈现。2."经 UL 允许从在线认证目录转载"声明必须出现在所摘取材料的邻近位置。此外,转载材料必须包含以下格式的版权声明:"© 2019 UL LLC"

Packaging & Delivery

Shipping service











	Quick Turn Lead Time					
Layer Count:	Lead Tim	Special Requirement				
1L/2L	2-3days	24 Hours,48 Hours				
4L	3-4days	48 Hours				
6L	4-5days	72 Hours				
8L	5-6days	NA				
10L	6-7days	NA				
12L	7-8days	NA				
14L	8-9days	NA				

	Standard Lead Time					
Layer Count:	Sample Lead Time	Volume order lead time				
2L	4 days	10 days				
4L	5 days	11 days				
6L	6 days	12 days				
8L	8 days	14 days				
10L	10 days	16 days				
12L	12 days	18 days				
14L	14 days	20 days				
16-32L	18 days	24 days				

Process Capability

PCB Production Capabilities

Layer Count: 1Layer-32Layer

Finished copper thickness 1/3oz-12oz

Min Line width/spacing internal ☐ 3.0mil/3.0mil Min Line width/spacing external: 4.0mil/4.0mil

Max Aspect Ratio: 10:1

Board thickness[] 0.2mm-5.0mm
Max Panel size(inches): 635*1500mm
Minimum Drilled Hole Size: 4mil
Plated Hole Tolerance: +/-3mil
Blind/Buried Vias (All Types): YES
Via Fill(Conductive,Non-Conductive): YES

Base Material: FR-4,FR-4high Tg.Halogen free material,Rogers,Aluminium base,Polyimide,

Heavy Copper

Surface finishes: HASL,OSP,ENIG,HAL-LF,Immersion silver,Immersion Tin,Gold fingers,Carbon ink

SMT Production Capabilities

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board

Max PCB size: 510x460mm Min PCB size 50x50mm PCB Thickness 0.5mm-4.5m

PCB Thickness□0.5mm-4.5mm Board thickness□0.5-4mm Min Components size: 0201

Standard chip size component: 0603 and larger

Component max height
☐15mm

Min lead pitch: 0.3mm Min BGA ball pitch:0.4mm

Placement precision: +/-0.03mm